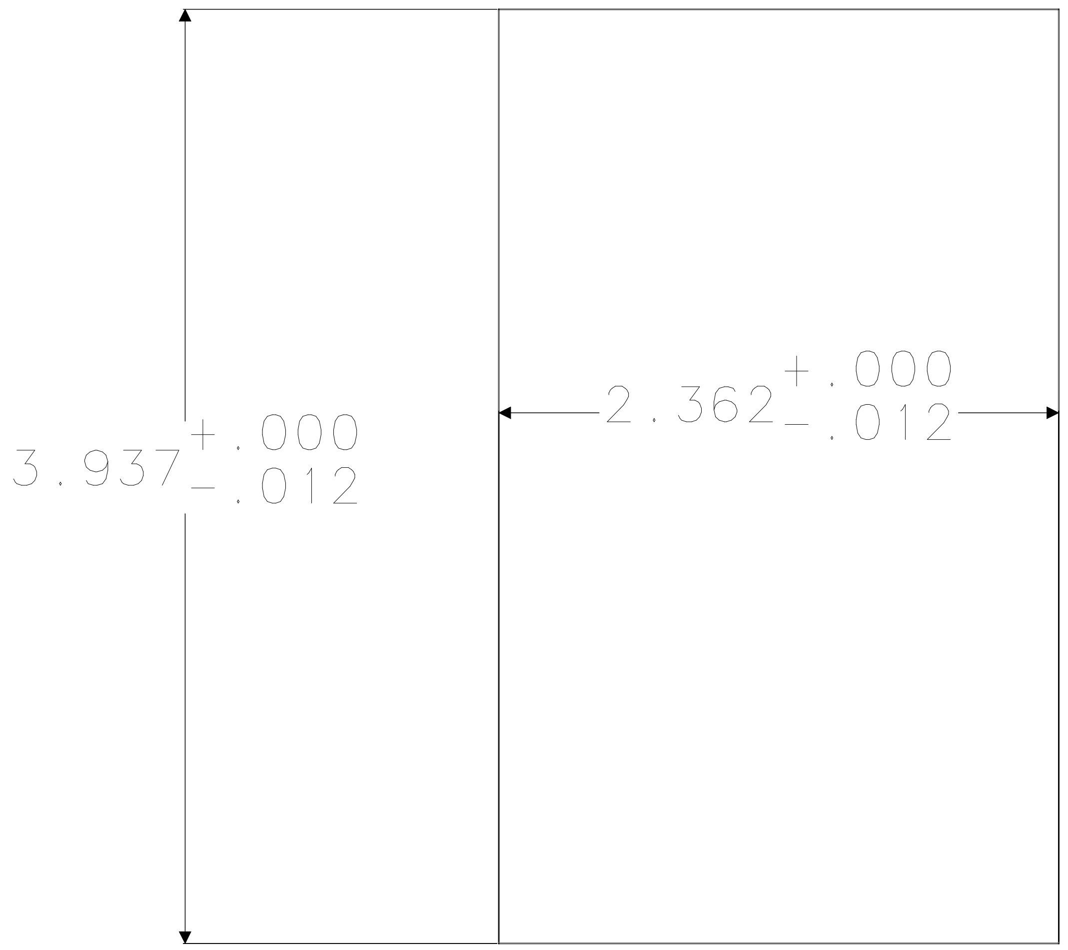
DWG. NO. A - 2797 | SH | REV. A



Board Characteristics

1. All dimensions are given in inches unless specified otherwise.
2. Minimum trace width: 0.005" on all layers
   Minimum clearence: 0.005" on all layers
3. Impedance Control: 50 Ohm for all 5-mil signal traces;
4. 1 oz Copper for Top, Bottom, and all Power layers;
   1/2 oz Copper for Stripline Trace layers;
5. Apply Solder Mask over bare copper.
6. Board Thickness: 0.063" +/- 0.008
7. Immersion Gold over Copper with min. Ni: 2.5-5 um; Au: 0.05-0.2 um;
8. Silkscreen on Component and Solder Sides.
10. FHS tolerances: +/- 0.003 unless specified otherwise.
11. Interlayer spacing as specified

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.01	166	YES	---	
⊞	.011811024	12	YES	---	
⦶	.035	16	YES	---	
⊟	.041	43	YES	---	
⊖	.057	4	YES	---	
◫	.062	4	YES	---	
⊕	.07	20	YES	---	
□	.104	4	YES	---	
	.12795276	4	YES	---	

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
.XX
.XXX
DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS		DATE
DRAWN	M.Bogdan	6/18/12
CHECKED	M.Bogdan	6/18/12
ISSUED		

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
GHz AC/DC PreAmp Board
Specification Drawing

SIZE | FSCM NO. | DWG. NO. 2797 | REV. A

SCALE 1/1 | SHEET

THIS SHEET IS COMPUTER GENERATED